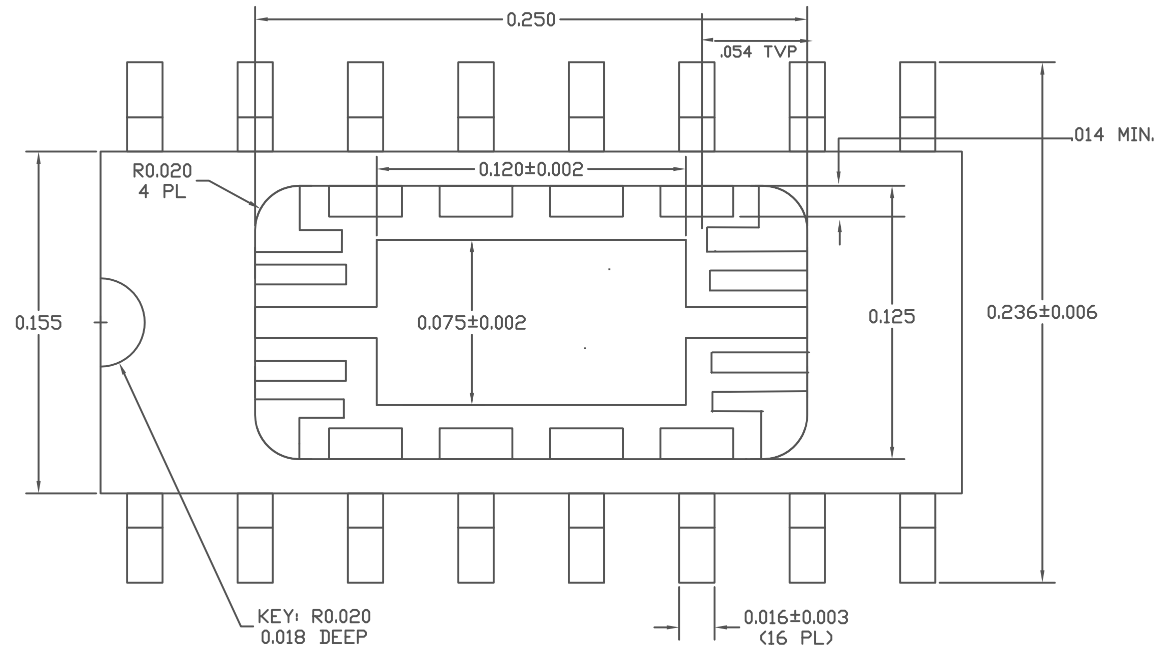
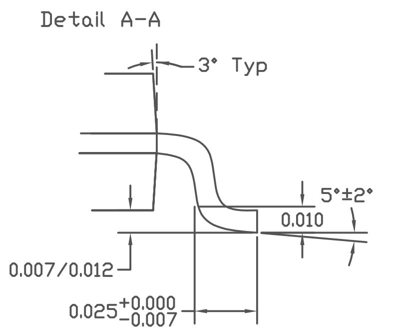
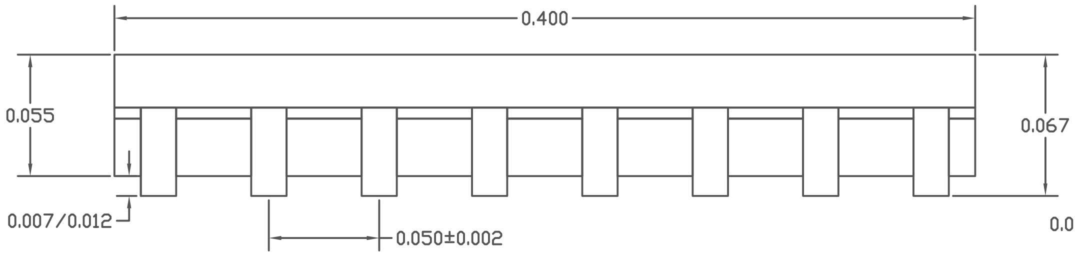
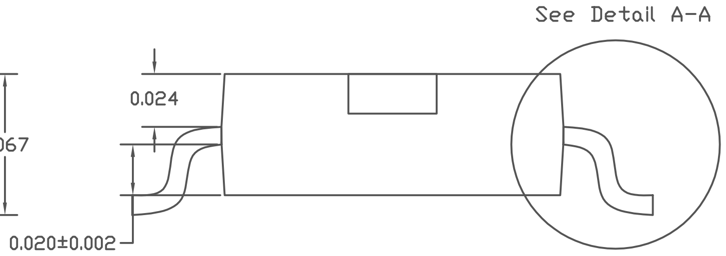
SSM P/N PSO161501

ECN	REV.	DESCRIPTION	DATE:	APP'D:
ECN	REV	ECNDESCRIPTION	ECNDATE	BF









NOTES:
BODY : Plastic, Semiconductor Grade
LEAD FRAME : Copper, Olin 194
LEAD FINISH : 50 uIN AU, Over 50uIN NI
DIE PAD .075" x .120"
Thickness : 0.008" +/- 0.001"

TITLE: SOIC 16 Lead		
MATERIAL: SEE NOTES	SCALE: NONE	DRAWN BY: DRAWNBY
GEN. TOL.: ±.005	DATE: DATE	APP'D: BF 2/21/01
DWG: SOIC16-OP-01		REV. REV

SPECTRUM
SEMICONDUCTOR MATERIALS, INC.